

**In the Claims**

Applicant submits a complete claim set, showing marked-up claims with insertions indicated by underlining and deletions indicated by strikeouts.

1. (Currently amended) A self-adhesive electronic circuit including a planar base having first and second base surfaces, an antenna attached on the first surface of the base, a chip connected to the antenna, and a double faced adhesive glued on one of the base surfaces, the double faced adhesive having an opening and the chip being arranged at least partially in the opening, wherein the ~~and a double faced adhesive having~~ has first and second adhesive surfaces, and wherein the first adhesive surface is glued on one of the base surfaces and the second adhesive surface forms an outward adhesive surface of the self-adhesive electronic circuit.

2. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein the chip is glued on the first surface of the base and is connected to the antenna by connection wires, the wires and the chip being covered with a drop of resin.

3. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein an etched surface of the chip faces the first surface of the base, and the chip is connected to the antenna by welding beads.

4. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein an etched surface of the chip faces the back of the first surface of the base, the chip is placed in a slot made through the base, and the chip is connected to the antenna by welding beads, the chip being attached to the base by a drop of resin.

5. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein an etched surface of the chip faces the back of the first surface of the base and the chip is connected to the antenna by welding beads located in connection slots going through the base, the chip being attached to the base by a drop of resin.

6. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein the base is made of a flexible sheet.

7. (Previously Presented) The self-adhesive electronic circuit of claim 1, wherein the surface of the base which does not receive the double faced adhesive is provided to receive printing of a pattern, of a text or of a code.

8. (Previously Presented) A method of manufacturing the self-adhesive electronic circuit of claim 1, wherein the attachment of the double faced adhesive on the base includes the steps of:

forming a rectangle of double faced adhesive including the opening,  
gluing the adhesive rectangle on a packaging protective film,  
ungluing the adhesive rectangle from the protective film, and assembling it on the base.

9. (Currently amended) An electronic circuit, comprising:  
a base having first and second surfaces;  
an antenna supported by the first surface of the base;  
a double faced adhesive having first and second surfaces, the first surface of the double faced adhesive being adhered to the first surface of the base, the double faced adhesive and  
having a thickness in a direction extending away from the first surface, the double faced adhesive having an opening, wherein at least a portion of the antenna is disposed in the opening; and  
an electronic chip disposed at least partially in the opening and electrically coupled to the antenna, the electronic chip having a height in a direction extending away from the first surface;  
wherein the thickness of the double faced adhesive is greater than or equal to the height of the electronic chip, and wherein the second surface of the double faced adhesive forms an outward adhesive surface of the electronic circuit that enables the electronic circuit to be adhered to a non-planar surface.

10. (Previously presented) The electronic circuit of claim 9, further comprising connection wires which electrically couple the electronic chip to the antenna and a resin which

covers the connection wires and the electronic chip, the resin having a height in a direction extending away from the first surface, wherein the thickness of the double faced adhesive is greater than or equal to the height of the resin.

11. (Previously presented) The electronic circuit of claim 9, further comprising welding beads which electrically couple the electronic chip to the antenna, wherein the chip has an etched surface which faces the first surface of the base.

12. (Previously presented) The electronic circuit of claim 9, further comprising welding beads which electrically couple the electronic chip to the antenna and a resin which attaches the electronic chip to the base, the base having a slot in which the electronic chip is arranged, the electronic chip having an etched surface which faces the base, the resin having a height in a direction extending away from the first surface, wherein the thickness of the double faced adhesive is greater than or equal to the height of the resin.

13. (Previously presented) The electronic circuit of claim 9, further comprising welding beads which electrically couple the electronic chip to the antenna and a resin which attaches the electronic chip to the base, the base having connection slots through which the welding beads reach the antenna, the electronic chip having an etched surface which faces the base, the resin having a height in a direction extending away from the first surface, wherein the thickness of the double faced adhesive is greater than or equal to the height of the resin.

14. (Previously presented) The electronic circuit of claim 9, wherein the base is composed of a flexible sheet.

15. (Previously presented) The electronic circuit of claim 9, wherein the surface of the base which does not receive the double faced adhesive is provided to receive printing of a pattern, text or code.

16. (Currently amended) An electronic circuit, comprising:  
a base having first and second surfaces;

an antenna supported by the first surface of the base;

a double faced adhesive having first and second surfaces, the first surface of the double faced adhesive being adhered to the first surface of the base, the double faced adhesive having an opening, wherein at least a portion of the antenna is disposed in the opening; and

an electronic chip disposed at least partially in the opening and electrically coupled to the antenna;

wherein the electronic chip is spaced from and does not contact the double faced adhesive, and the second surface of the double faced adhesive forms an outward adhesive surface of the electronic circuit that enables the electronic circuit to be adhered to a non-planar surface.

17. (Previously presented) The electronic circuit of claim 16, further comprising connection wires which electrically couple the electronic chip to the antenna and a resin which covers the connection wires and the electronic chip.

18. (Previously presented) The electronic circuit of claim 16, further comprising welding beads which electrically couple the electronic chip to the antenna, wherein the electronic chip has an etched surface which faces the first surface of the base.

19. (Previously presented) The electronic circuit of claim 16, further comprising welding beads which electrically couple the electronic chip to the antenna and a resin which attaches the electronic chip to the base, the base having a slot in which the electronic chip is arranged, the electronic chip having an etched surface which faces the base.

20. (Previously presented) The electronic circuit of claim 16, further comprising welding beads which electrically couple the electronic chip to the antenna and a resin which attaches the electronic chip to the base, the base having connection slots through which the welding beads reach the antenna, the electronic chip having an etched surface which faces the base.

21. (Previously presented) The electronic circuit of claim 16, wherein the base is composed of a flexible sheet.

22. (Previously presented) The electronic circuit of claim 16, wherein the surface of the base which does not receive the double faced adhesive is provided to receive printing of a pattern, text or code.

23. (Previously presented) The electronic circuit of claim 1, wherein the double faced adhesive comprises a double faced adhesive tape.

24. (New) A method of using the self-adhesive electronic circuit of claim 1, comprising an act of:

(A) adhering the outward adhesive surface of the self-adhesive electronic circuit to a non-planar surface.